

ADC774

Microprocessor-Compatible ANALOG-TO-DIGITAL CONVERTER

FEATURES

- **COMPLETE 12-BIT A/D CONVERTER WITH REFERENCE, CLOCK, AND 8-, 12-, or 16-BIT MICROPROCESSOR BUS INTERFACE**
- **ALTERNATE SOURCE FOR HI774 A/D CONVERTER: 8.5 μ s Conversion Time, 150ns Bus Access Time**
- **FULLY SPECIFIED FOR OPERATION ON ± 12 V OR ± 15 V SUPPLIES**
- **NO MISSING CODES OVER TEMPERATURE:**
0 $^{\circ}$ C to +75 $^{\circ}$ C: ADC774J, K
-55 $^{\circ}$ C to +125 $^{\circ}$ C: ADC774SH, TH

DESCRIPTION

The ADC774 is a 12-bit successive approximation analog-to-digital converter, utilizing state-of-the-art CMOS and laser-trimmed bipolar die custom-designed for freedom from latch-up and for optimum AC per-

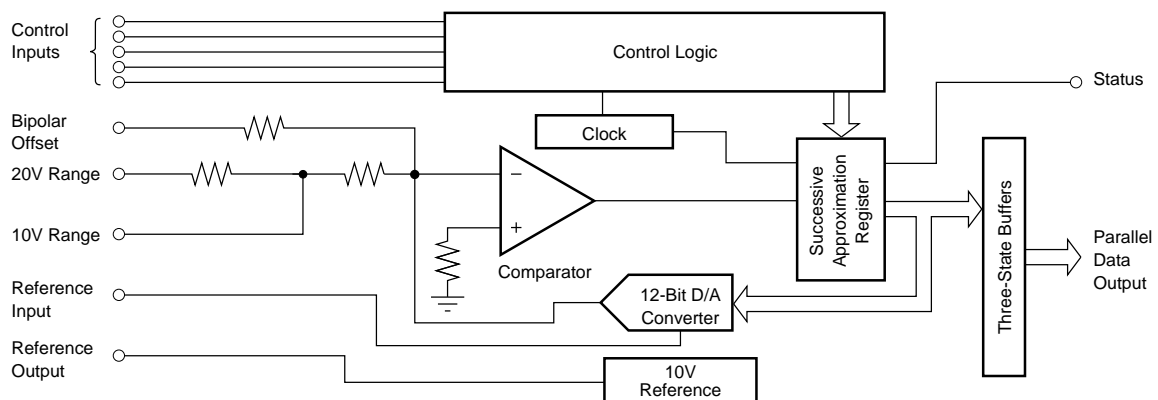
formance. It is complete with a self-contained +10V reference, internal clock, digital interface for microprocessor control, and three-state outputs.

The reference circuit, containing a buried zener, is laser-trimmed for minimum temperature coefficient. The clock oscillator is current-controlled for excellent stability over temperature. Full-scale and offset errors may be externally trimmed to zero. Internal scaling resistors are provided for the selection of analog input signal ranges of 0V to +10V, 0V to +20V, ± 5 V, and ± 10 V.

The converter may be externally programmed to provide 8- or 12-bit resolution. The conversion time for 12 bits is factory set for 8.5 μ s maximum.

Output data are available in a parallel format from TTL-compatible three-state output buffers. Output data are coded in straight binary for unipolar input signals and bipolar offset binary for bipolar input signals.

The ADC774, available in both industrial and military temperature ranges, requires supply voltages of +5V and ± 12 V or ± 15 V. It is packaged in a 28-pin plastic DIP, or a hermetic side-brazed ceramic DIP.



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 Tel: (520) 746-1111 • Twx: 910-952-1111 • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS

ELECTRICAL

$T_A = +25^\circ\text{C}$, $V_{CC} = +12\text{V}$ or $+15\text{V}$, $V_{EE} = -12\text{V}$ or -15V , $V_{LOGIC} = +5\text{V}$ unless otherwise specified.

PARAMETER	ADC774J, ADC774SH			ADC774K, ADC774TH			UNITS
	MIN	TYP	MAX	MIN	TYP	MAX	
RESOLUTION			12			*	Bits
INPUTS							
ANALOG Voltage Ranges: Unipolar Bipolar Impedance: 0 to +10V, $\pm 5\text{V}$ $\pm 10\text{V}$, 0V to +20V	0 to +10, 0 to +20 ± 5 , ± 10				*	*	V V k Ω k Ω
DIGITAL (CE, $\overline{\text{CS}}$, R/ $\overline{\text{C}}$, A _O , 12/8) Over Temperature Range Voltages: Logic 1 Logic 0 Current Capacitance	+2 -0.5 -5		+5.5 +0.8 +5	*	*	*	V V μA pF
TRANSFER CHARACTERISTICS							
ACCURACY At +25°C Linearity Error Unipolar Offset Error (Adjustable to Zero) Bipolar Offset Error (Adjustable to Zero) Full-Scale Calibration Error ⁽¹⁾ (Adjustable to Zero) No Missing Codes Resolution (Diff. Linearity) Inherent Quantization Error T_{MIN} to T_{MAX} Linearity Error: J, K Grades S, T Grades Full-Scale Calibration Error Without Initial Adjustment ⁽¹⁾ : J, K Grades S, T Grades Adjusted to Zero at +25°C: J, K Grades S, T Grades No Missing Codes Resolution (Diff. Linearity)	11	$\pm 1/2$	± 1 ± 2 ± 10 ± 0.25	12	*	$\pm 1/2$ * ± 4 * $\pm 1/2$ $\pm 3/4$ ± 0.37 ± 0.5 ± 0.12 ± 0.25	LSB LSB LSB % of FS ⁽²⁾ Bits LSB LSB LSB % of FS % of FS % of FS % of FS Bits
TEMPERATURE COEFFICIENTS (T_{MIN} to T_{MAX}) ⁽³⁾ Unipolar Offset: J, K Grades S, T Grades Max Change: All Grades Bipolar Offset: All Grades Max Change: J, K Grades S, T Grades Full-Scale Calibration: J, K Grades S, T Grades Max Change: J, K Grades S, T Grades			± 10 ± 5 ± 2 ± 10 ± 2 ± 4 ± 45 ± 50 ± 9 ± 20			± 5 ± 2.5 ± 1 ± 5 ± 1 ± 2 ± 25 ± 25 ± 5 ± 10	ppm/°C ppm/°C LSB ppm/°C LSB LSB ppm/°C ppm/°C LSB LSB
POWER SUPPLY SENSITIVITY Change in Full-Scale Calibration $+13.5\text{V} < V_{CC} < +16.5\text{V}$ or $+11.4\text{V} < V_{CC} < +12.6\text{V}$ $-16.5\text{V} < V_{EE} < -13.5\text{V}$ or $-12.6\text{V} < V_{EE} < -11.4\text{V}$ $+4.5\text{V} < V_{LOGIC} < +5.5\text{V}$			± 2 ± 2 $\pm 1/2$			± 1 ± 1 *	LSB LSB LSB
CONVERSION TIME ^(4,5) 8-Bit Cycle 12-Bit Cycle		5 7.5	5.3 8.5		*	*	μs μs
OUTPUTS							
DIGITAL (DB11 – DB0, STATUS) (Over Temperature Range) Output Codes: Unipolar Bipolar Logic Levels: Logic 0 ($I_{SINK} = 1.6\text{mA}$) Logic 1 ($I_{SOURCE} = 500\mu\text{A}$) Leakage, Data Bits Only, High-Z State Capacitance	+2.4 -5	0.1 5	Unipolar Straight Binary (USB) Bipolar Offset Binary (BOB) $+0.4$ $+5$		*	*	V V μA pF

SPECIFICATIONS (CONT)

ELECTRICAL

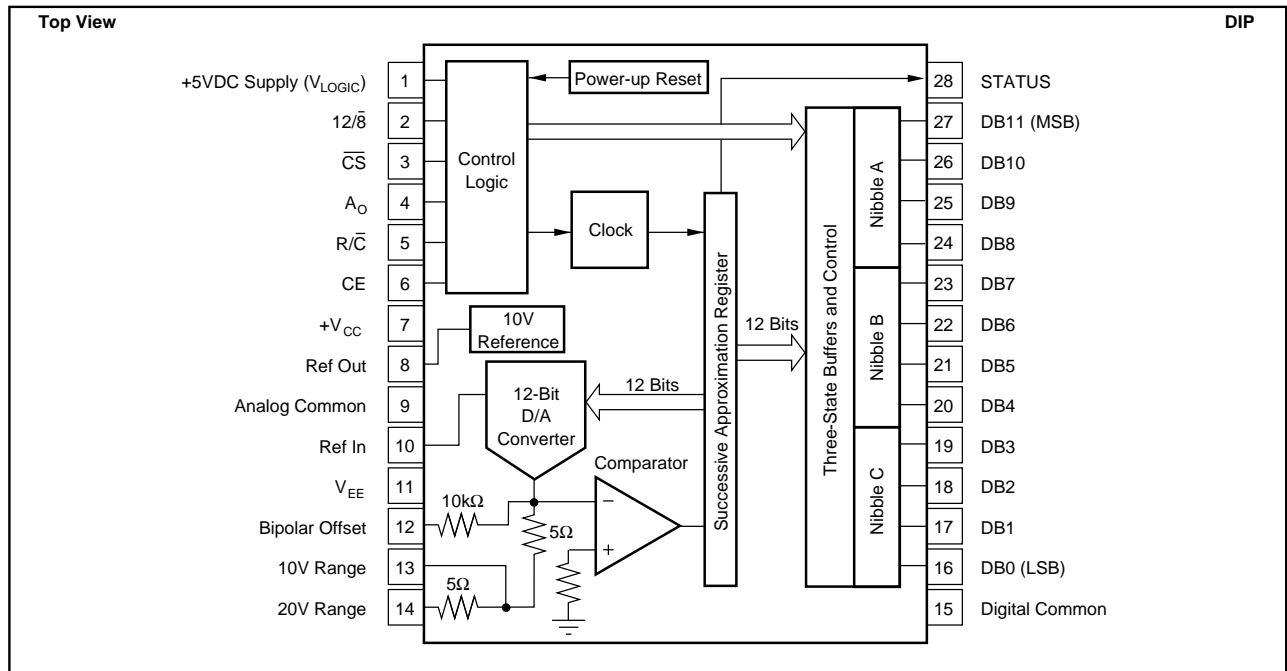
$T_A = +25^\circ\text{C}$, $V_{CC} = +12\text{V}$ or $+15\text{V}$, $V_{EE} = -12\text{V}$ or -15V , $V_{LOGIC} = +5\text{V}$ unless otherwise specified.

PARAMETER	ADC774J, ADC774SH			ADC774K, ADC774TH			UNITS
	MIN	TYP	MAX	MIN	TYP	MAX	
INTERNAL REFERENCE VOLTAGE							
Voltage	+9.9	+10	+10.1	*	*	*	V
Source Current Available for External Loads ⁽⁶⁾	2.0			*			mA
POWER SUPPLY REQUIREMENTS							
Voltage: V_{CC}	+11.4		+16.5	*		*	V
V_{EE}	-11.4		-16.5	*		*	V
V_{LOGIC}	+4.5		+5.5	*		*	V
Current: I_{CC}		3.5	5		*	*	mA
I_{EE}		15	20		*	*	mA
I_{LOGIC}		9	15		*	*	mA
Power Dissipation ($\pm 15\text{V}$ Supplies)		325	450		*	*	mW
TEMPERATURE RANGE (Ambient: T_{MIN}, T_{MAX})							
Specifications: J, K Grades	0		+75	*		*	$^\circ\text{C}$
S, T Grades	-55		+125	*		*	$^\circ\text{C}$
Storage	-65		+150	*		*	$^\circ\text{C}$

*Same specification as ADC774JH, JP, SH.

NOTES: (1) With fixed 50Ω resistor from Ref Out to Ref In. This parameter is also adjustable to zero at $+25^\circ\text{C}$. (2) FS in this specification table means Full Scale Range. That is, for a $\pm 10\text{V}$ input range FS means 20V ; for a 0V to $+10\text{V}$ range, FS means 10V . The term Full Scale for these specification instead of Full-Scale Range is used to be consistent with other vendors' specifications tables. (3) Using internal reference. (4) See "Controlling the ADC774" section for detailed information concerning digital timing. (5) The Harris HI-774 uses a subranging/error correction technique that allows one to begin conversion before a preceding sample-hold or multiplexer has settled to $\pm 1/2\text{LSB}$. For 12-bit accurate conversions, the input transient to the ADC774 must settle to less than $\pm 1/2\text{LSB}$ before conversion is started. The ADC774 is compatible with HI-774 in all other respects. (6) External loading must be constant during conversion. The reference output requires no buffer amplifier with either $\pm 12\text{V}$ or $\pm 15\text{V}$ power supplies.

PIN CONFIGURATION



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ABSOLUTE MAXIMUM RATINGS

V _{CC} to Digital Common	0V to +16.5V
V _{EE} to Digital Common	0V to -16.5V
V _{LOGIC} Digital Common	0V to +7V
Analog Common to Digital Common	±1V
Control Inputs (CE, \overline{CS} , A ₀ , 12/8, R \overline{C})	
to Digital Common	-0.5V to V _{LOGIC} +0.5V
Analog Inputs (Ref In, Bipolar Offset, 10V _{IN})	
to Analog Common	±16.5V
20V _{IN} to Analog Common	±24V
Ref Out	Indefinite Short to Common, Momentary Short to V _{CC}
Max Junction Temperature	+165°C
Power Dissipation	1000mW
Lead Temperature (soldering, 10s)	+300°C
Thermal Resistance, θ_{JA} : Ceramic	50°C/W
Plastic	100°C/W

CAUTION: These devices are sensitive to electrostatic discharge. Appropriate I.C. handling procedures should be followed.

BURN-IN SCREENING

Burn-in screening is available for both plastic and ceramic package ADC774s. Burn-in duration is 160 hours at the temperature (or equivalent combination of time and temperature) indicated below:

Plastic “-BI” models: +85°C

Ceramic “-BI” models: +125°C

All units are 100% electrically tested after burn-in is completed. To order burn-in, add “-BI” to the base model number (e.g. ADC774KP-BI). See Ordering Information for pricing.

PACKAGE INFORMATION

MODEL	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
ADC774JP	28-Pin Plastic DIP	215
ADC774KP	28-Pin Plastic DIP	215
ADC774JH	28-Pin Ceramic DIP	149
ADC774KH	28-Pin Ceramic DIP	149
ADC774SH	28-Pin Ceramic DIP	149
ADC774TH	28-Pin Ceramic DIP	149
ADC774JP-BI	28-Pin Plastic DIP	215
ADC774KP-BI	28-Pin Plastic DIP	215
ADC774JH-BI	28-Pin Ceramic DIP	149
ADC774KH-BI	28-Pin Ceramic DIP	149
ADC774SH-BI	28-Pin Ceramic DIP	149
ADC774TH-BI	28-Pin Ceramic DIP	149

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix D of Burr-Brown IC Data Book.

ORDERING INFORMATION

MODEL	PACKAGE	TEMPERATURE RANGE	LINEARITY ERROR MAX (T _{MIN} TO T _{MAX})
ADC774JP	Plastic DIP	0°C TO +75°C	±1LSB
ADC774KP	Plastic DIP	0°C to +75°C	±1/2LSB
ADC774JH	Ceramic DIP	0°C to +75°C	±1LSB
ADC774KH	Ceramic DIP	0°C to +75°C	±1/2LSB
ADC774SH	Ceramic DIP	-55°C to +125°C	±1LSB
ADC774TH	Ceramic DIP	-55°C to +125°C	±3/4LSB
BURN-IN SCREENING OPTION See text for details.			
MODEL	PACKAGE	TEMPERATURE RANGE	BURN-IN TEMP (160 HOURS) ⁽¹⁾
ADC774JP-BI	Plastic DIP	0°C to +75°C	+85°C
ADC774KP-BI	Plastic DIP	0°C to +75°C	+85°C
ADC774JH-BI	Ceramic DIP	0°C to +75°C	+125°C
ADC774KH-BI	Ceramic DIP	0°C to +75°C	+125°C
ADC774SH-BI	Ceramic DIP	-55°C to +125°C	+125°C
ADC774TH-BI	Ceramic DIP	-55°C to +125°C	+125°C

CONTROLLING THE ADC774

This is an abridged data sheet. For Discussion of Specifications, Installation, Calibration refer to ADC574A data sheet or order PDS-835.

The Burr-Brown ADC774 can be easily interfaced to most microprocessor systems and other digital systems. The microprocessor may take full control of each conversion, or the converter may operate in a stand-alone mode, controlled only by the R/\bar{C} input. Full control consists of selecting an 8- or 12-bit conversion cycle, initiating the conversion, and reading the output data when ready—choosing either 12 bits all at once, or 8 bits followed by 4 bits in a left-justified format. The five control inputs ($12/\bar{8}$, $\bar{C}\bar{S}$, A_0 , R/\bar{C} , and CE) are all TTL-/CMOS-compatible. The functions of the control inputs are described in Table I. The control function truth table is listed in Table II.

Read footnote 5 to the Electrical Specifications table if using ADC774 to replace the HI-774.

STAND-ALONE OPERATION

For stand-alone operation, control of the converter is accomplished by a single control line connected to R/\bar{C} . In this mode $\bar{C}\bar{S}$ and A_0 are connected to digital common and CE and $12/\bar{8}$ are connected to V_{LOGIC} (+5V). The output data are presented as 12-bit words. The stand-alone mode is used in systems containing dedicated input ports which do not require full bus interface capability.

Conversion is initiated by a high-to-low transition of R/\bar{C} . The three-state data output buffers are enabled when R/\bar{C} is high and STATUS is low. Thus, there are two possible modes of operation; conversion can be initiated with either positive or negative pulses. In either case the R/\bar{C} pulse must remain low for a minimum of 50ns.

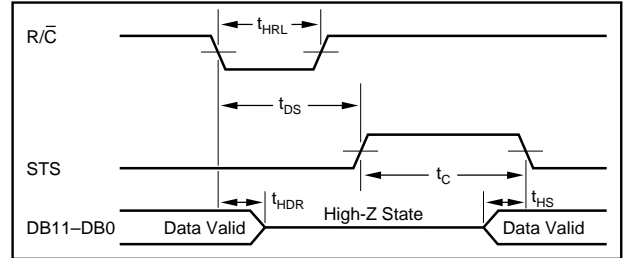


FIGURE 1. R/\bar{C} Pulse Low—Outputs Enabled After Conversion.

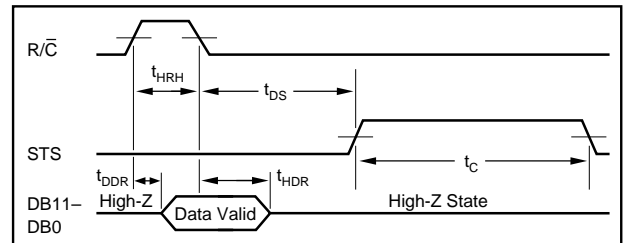


FIGURE 2. R/\bar{C} Pulse High—Outputs Enabled Only While R/\bar{C} Is High.

PIN DESIGNATION	DEFINITION	FUNCTION
CE (Pin 6)	Chip Enable (active high)	Must be high ("1") to either initiate a conversion or read output data. 0-1 edge may be used to initiate a conversion.
$\bar{C}\bar{S}$ (Pin 3)	Chip Select (active low)	Must be low ("0") to either initiate a conversion or read output data. 1-0 edge may be used to initiate a conversion.
R/\bar{C} (Pin 5)	Read/Convert ("1" = read) ("0" = convert)	Must be low ("0") to initiate either 8- or 12-bit conversions. 1-0 edge may be used to initiate a conversion. Must be high ("1") to read output data. 0-1 edge may be used to initiate a read operation.
A_0 (Pin 4)	Byte Address Short Cycle	In the start-convert mode, A_0 selects 8-bit ($A_0 = "1"$) or 12-bit ($A_0 = "0"$) conversion mode. When reading output data in two 8-bit bytes, $A_0 = "0"$ accesses 8 MSBs (high byte) and $A_0 = "1"$ accesses 4 LSBs and trailing "0s" (low byte).
$12/\bar{8}$ (Pin 2)	Data Mode Select ("1" = 12 bits) ("0" = 8 bits)	When reading output data, $12/\bar{8} = "1"$ enables all 12 output bits simultaneously. $12/\bar{8} = "0"$ will enable the MSBs or LSBs as determined by the A_0 line.

TABLE I. ADC774 Control Line Functions.

CE	$\bar{C}\bar{S}$	R/\bar{C}	$12/\bar{8}$	A_0	OPERATION
0	X	X	X	X	None
X	1	X	X	X	None
↑	0	0	X	0	Initiate 12-bit conversion
↑	0	0	X	1	Initiate 8-bit conversion
1	↓	0	X	0	Initiate 12-bit conversion
1	↓	0	X	1	Initiate 8-bit conversion
1	0	↓	X	0	Initiate 12-bit conversion
1	0	↓	X	1	Initiate 8-bit conversion
1	0	1	1	X	Enable 12-bit output
1	0	1	0	0	Enable 8 MSBs only
1	0	1	0	1	Enable 4 LSBs plus 4 trailing zeros

TABLE II. Control Input Truth Table.

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
t_{HRL}	Low R/\bar{C} Pulse Width	50			ns
t_{DS}	STS Delay from R/\bar{C}			200	ns
t_{HDR}	Data Valid After R/\bar{C} Low	25			ns
t_{HS}	STS Delay After Data Valid		150	375	ns
t_{HRH}	High R/\bar{C} Pulse Width	150			ns
t_{DDR}	Data Access Time			150	ns

TABLE III. Stand-Alone Mode Timing.

Figure 1 illustrates timing when conversion is initiated by an R/\bar{C} pulse which goes low and returns to the high state during the conversion. In this case, the three-state outputs go to the high-impedance state in response to the falling edge of R/\bar{C} and are enabled for external access of the data after completion of the conversion. Figure 2 illustrates the timing when conversion is initiated by a positive R/\bar{C} pulse. In this mode the output data from the previous conversion is enabled during the positive portion of R/\bar{C} . A new conversion is started on the falling edge of R/\bar{C} , and the three-state outputs return to the high-impedance state until the next occurrence of a high R/\bar{C} pulse. Timing specifications for stand-alone operation are listed in Table III.

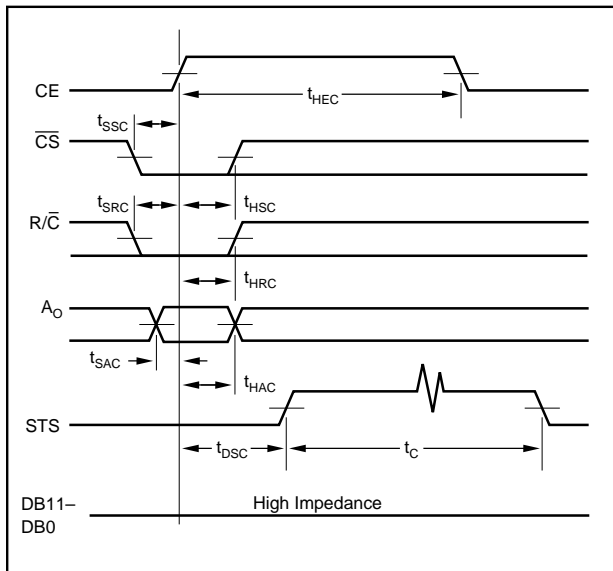


FIGURE 3. Conversion Cycle Timing.

FULLY CONTROLLED OPERATION

Conversion Length

Conversion length (8-bit or 12-bit) is determined by the state of the A_0 input, which is latched upon receipt of a conversion start transition (described below). If A_0 is latched high, the conversion continues for 8 bits. The full 12-bit conversion will occur if A_0 is low. If all 12 bits are read following an 8-bit conversion, the 3 LSBs (DB0–DB2) will be low (logic 0) and DB3 will be high (logic 1). A_0 is latched because it is also involved in enabling the output buffers. No other control inputs are latched.

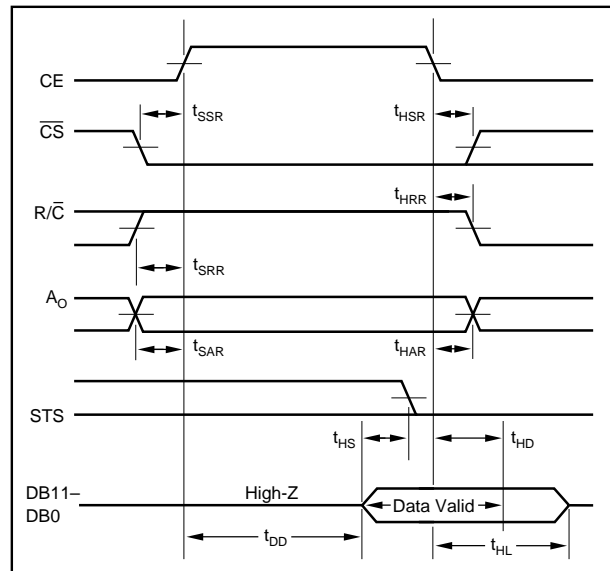


FIGURE 4. Read Cycle Timing.

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
t_{DSC}	STS Delay from CE		60	200	ns
t_{HEC}	CE Pulse Width	50	30		ns
t_{SSC}	\bar{CS} to CE Setup time	50	20		ns
t_{HSC}	\bar{CS} low during CE high	50	20		ns
t_{SRC}	R/\bar{C} to CE setup	50	0		ns
t_{HRC}	R/\bar{C} low during CE high	50	20		ns
t_{SAC}	A_0 to CE setup	0			ns
t_{HAC}	A_0 valid during CE high	50	20		ns
t_C	Conversion time				
	12-bit cycle at 25°C		7.5	8.5	μs
	0 to +75°C			9.0	μs
	-55°C to +125°C			9.5	μs
	8-bit cycle at 25°C		5	5.3	μs
	0 to +75°C			5.6	μs
	-55° to +125°C			6	μs
Read Mode					
t_{DD}	Access time from CE		75	150	ns
t_{HD}	Data valid after CE low	25	35		ns
t_{HL}	Output float delay		100	150	ns
t_{SSR}	\bar{CS} to CE setup	50	0		ns
t_{SAR}	R/\bar{C} to CE setup	0			ns
t_{HSR}	\bar{CS} valid after CE low	0			ns
t_{HRR}	R/\bar{C} high after CE low	0			ns
t_{HAR}	A_0 valid after CE low	50			ns
t_{HS}	STS delay after data valid		150	375	ns

TABLE IV. Timing Specifications.

CONVERSION START

The converter is commanded to initiate a conversion by a transition occurring on any of three logic inputs (\overline{CE} , CS , and R/\overline{C}) as shown in Table II. Conversion is initiated by the last of the three to reach the required state and thus all three may be dynamically controlled. If necessary, all three may change state simultaneously, and the nominal delay time is the same regardless of which input actually starts conversion. If it is desired that a particular input establish the actual start of conversion, the other two should be stable a minimum of 50ns prior to the transition of that input. Timing relationships for start of conversion timing are illustrated in Figure 3. The specifications for timing are contained in Table IV.

The STATUS output indicates the current state of the converter by being in a high state only during conversion. During this time the three-state output buffers remain in a high-impedance state, and therefore data cannot be read during conversion. During this period additional transitions

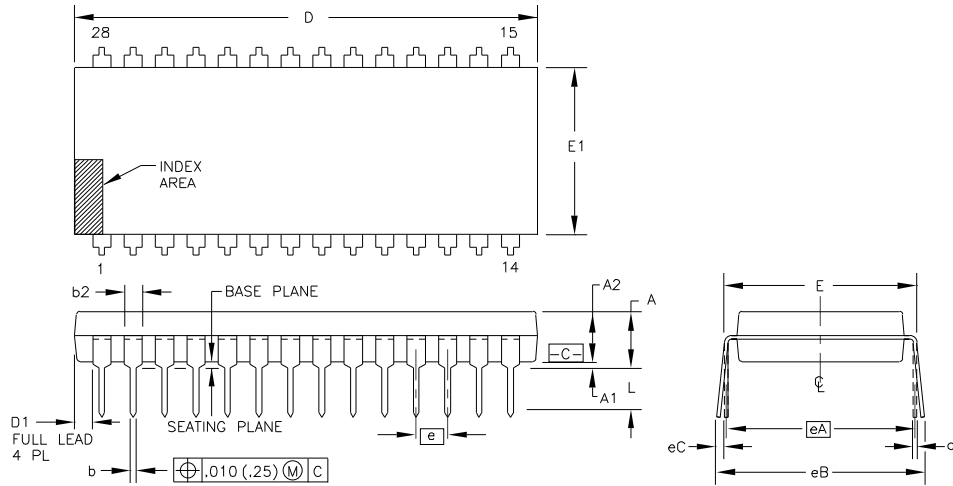
of the three digital inputs which control conversion will be ignored, so that conversion cannot be prematurely terminated or restarted. However, if A_O changes state after the beginning of conversion, any additional start conversion transition will latch the new state of A_O , possibly resulting in an incorrect conversion length (8 bits vs 12 bits) for that conversion.

READING OUTPUT DATA

After conversion is initiated, the output data buffers remain in a high-impedance state until the following four logic conditions are simultaneously met: R/\overline{C} high, STATUS low, CE high, and \overline{CS} low. Upon satisfaction of these conditions the data lines are enabled according to the state of inputs $12/\overline{8}$ and A_O . See Figure 4 and Table IV for timing relation-

PACKAGE DRAWINGS

Package Number 215 - 28-Pin Plastic, Double-Wide DIP



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	--	.250	--	6.35	3		L	.115	.200	2.92	5.08	3	
A1	.015	--	0.38	--	3		N			28		28	7
A2	.125	.195	3.18	4.95									
b	.014	.022	0.36	0.56									
b2	.030	.070	0.76	1.78	9								
c	.008	.015	0.20	0.38									
D	1.380	1.565	35.05	39.75	4								
D1	.005	--	0.13	--	4								
E	.600	.625	15.24	15.88	5								
E1	.485	.580	12.32	14.73	4								
e	.100	BASIC	2.54	BASIC									
eA	.600	BASIC	15.26	BASIC	5								
eB	--	.700	--	17.78	6								
eC	.000	.060	0.00	1.52	6								

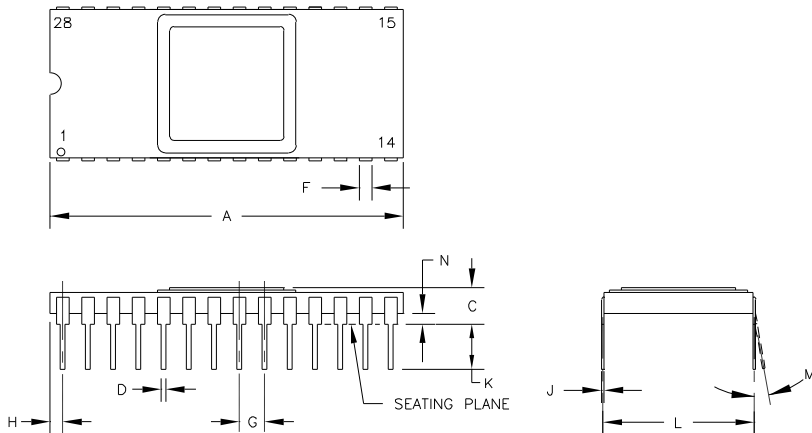
NOTES:

1. ALL DIMENSIONS ARE IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
3. DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
5. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM C .
6. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. N IS THE MAXIMUM OF TERMINAL POSITIONS.

8. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
9. b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
10. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.
11. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
12. FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.

PACKAGE NUMBER: ZZ215 REV.: J
JEDEC NUMBER: MS-011-AB

Package Number 149 - 28-Pin Hermetic Ceramic DIP



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	1.386	1.414	35.20	35.92									
C	.115	.175	2.92	4.45									
D	.015	.021	0.38	0.53									
F	.035	.060	0.89	1.52									
G	.100	BASIC	2.54	BASIC									
H	.036	.064	0.91	1.63									
J	.008	.012	0.20	0.30									
K	.120	.240	3.05	6.10									
L	.600	BASIC	15.24	BASIC									
M	--	10"	--	10"									
N	.025	.060	0.64	1.52									

NOTES:

1. LEADS IN TRUE POSITION WITHIN .010" (.25mm) R @ MMC AT SEATING PLANE.
2. PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.

PACKAGE NUMBER: ZZ149 REV.: B
JEDEC NUMBER: MO-038 WITH EXCEPTIONS